What is claimed is:

1. A heat pipe system comprising:

   a heat transfer block; and,

   a heat pipe coupled to the heat transfer block by a clip.

2. The heat pipe system of claim 1, wherein the clip includes a main surface and two side surfaces disposed substantially orthogonal to the main surface.

3. The heat pipe system of claim 1, wherein the heat transfer block includes at least one clip channel disposed therein for receiving the clip.

4. The heat pipe system of claim 1, wherein the heat transfer block includes at least two clip channels disposed therein for receiving the clip.

5. The heat pipe system of claim 1, wherein the heat transfer block includes at least one heat pipe channel disposed therein for receiving the heat pipe.

6. The heat pipe system of claim 5, wherein the heat pipe includes a main portion and a pinchoff portion, wherein the pinchoff portion is disposed in the heat pipe channel.

7. The heat pipe system of claim 5, wherein the heat pipe is coupled to the heat pipe channel by solder.

8. The heat pipe system of claim 5, wherein the heat pipe is coupled to the heat pipe channel by epoxy.

9. The heat pipe system of claim 5, wherein the heat pipe is coupled to the heat pipe channel by friction.

10. The heat pipe system of claim 5, wherein the heat pipe is coupled to the heat pipe channel by at least one fastener.

11. The heat pipe system of claim 2, wherein the heat transfer block includes at least one clip channel disposed therein for receiving the clip, such that the two side surfaces of the clip are disposed in the at least one clip channel.

12. The heat pipe system of claim 11, wherein the clip is coupled to the at least two clip channels by solder.

13. The heat pipe system of claim 11, wherein the clip is coupled to the at least two clip channels by epoxy.

14. The heat pipe system of claim 11, wherein the clip is coupled to the at least two clip channels by friction.

15. The heat pipe system of claim 11, wherein the heat pipe is coupled to the heat pipe channel by at least one fastener.

16. The heat pipe system of claim 2, wherein the heat transfer block includes at least two clip channels disposed therein for receiving the clip, such that the two side surfaces of the clip are disposed in the at least two clip channels.

17. The heat pipe system of claim 16, wherein the clip is coupled to the at least two clip channels by solder.

18. The heat pipe system of claim 16, wherein the clip is coupled to the at least two clip channels by epoxy.

19. The heat pipe system of claim 16, wherein the clip is coupled to the at least two clip channels by friction.

20. The heat pipe system of claim 16, wherein the heat pipe is coupled to the heat pipe channel by at least one fastener.

21. The heat pipe system of claim 1, wherein the clip includes a top surface and bottom surface with at least two tabs extending orthogonally from the bottom surface.

22. The heat pipe system of claim 21, wherein the heat transfer block includes at least two channels for receiving the at least two tabs in the clip.

23. The heat pipe system of claim 1, wherein the clip extends substantially across an entire top surface of the heat transfer block.

24. A computer comprising:

at least one electronic component;

a heat transfer block disposed adjacent to the at least one electronic component; and,

a heat pipe coupled to the heat transfer block by a clip.

25. A method for cooling a heat-producing element, comprising the steps of:

disposing a heat transfer block adjacent the heat-producing element;

coupling the heat transfer block to a heat pipe using a clip.

26. A method for manufacturing a heat pipe assembly, comprising the steps of:

forming a heat transfer block with at least one heat pipe channel and at least one clip channel disposed therein;

bonding a heat pipe to the heat pipe channel; and

bonding a clip to the at least one clip channel, such that the clip overlies at least a portion of the heat pipe.

27. The method of claim 26, wherein the steps of bonding the heat pipe and bonding the clip comprise bonding by solder.

28. The method of claim 26, wherein the steps of bonding the heat pipe and bonding the clip comprise bonding by epoxy.

29. The method of claim 26, wherein the steps of bonding the heat pipe and bonding the clip comprise bonding by fasteners.